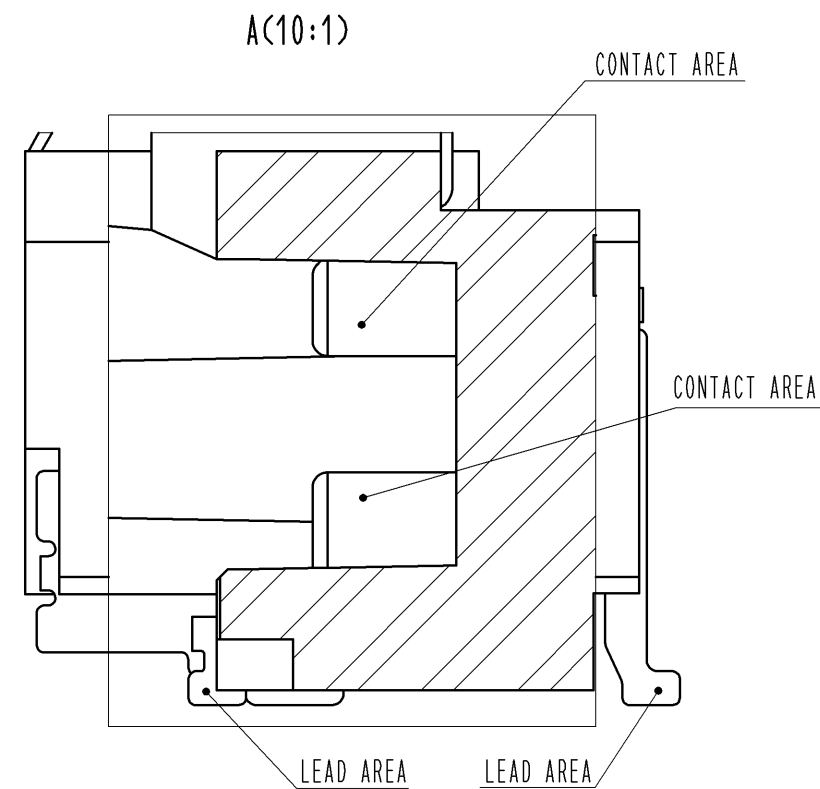
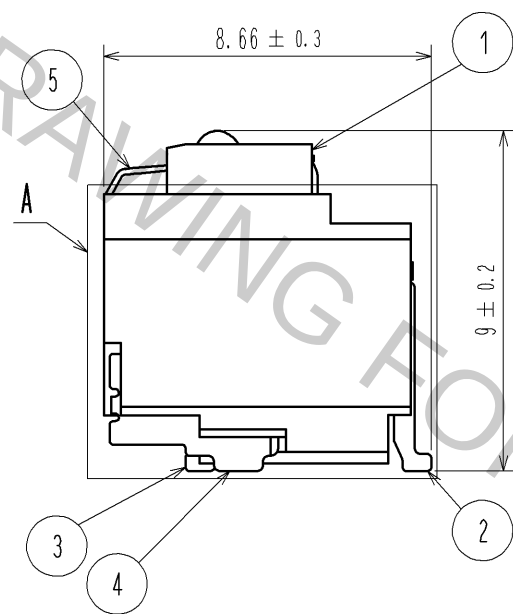


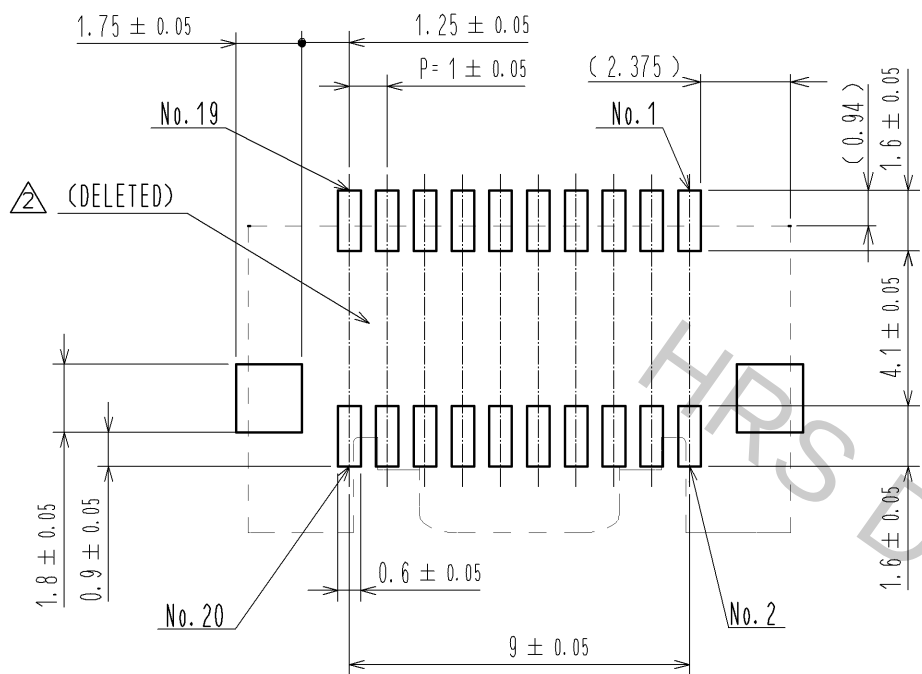


3	BRASS	CONTACT AREA : Au PLATING 0.05μm MIN LEAD AREA : Au PLATING 0.05μm MIN UNDER PLATING : Ni PLATING 1μm MIN	8	PS	REEL, BLACK
2	BRASS	CONTACT AREA : Au PLATING 0.05μm MIN LEAD AREA : Au PLATING 0.05μm MIN UNDER PLATING : Ni PLATING 1μm MIN	7	POLYESTER	CLEAR
			6	PS	CLEAR
			5	STAINLESS STEEL	—
1	LCP	BLACK, UL94V-0	4	BRASS	CONTACT AREA : Sn PLATING 1μm MIN UNDER PLATING : Ni PLATING 0.5μm MIN
NO.	MATERIAL	FINISH , REMARKS	NO.	MATERIAL	FINISH , REMARKS

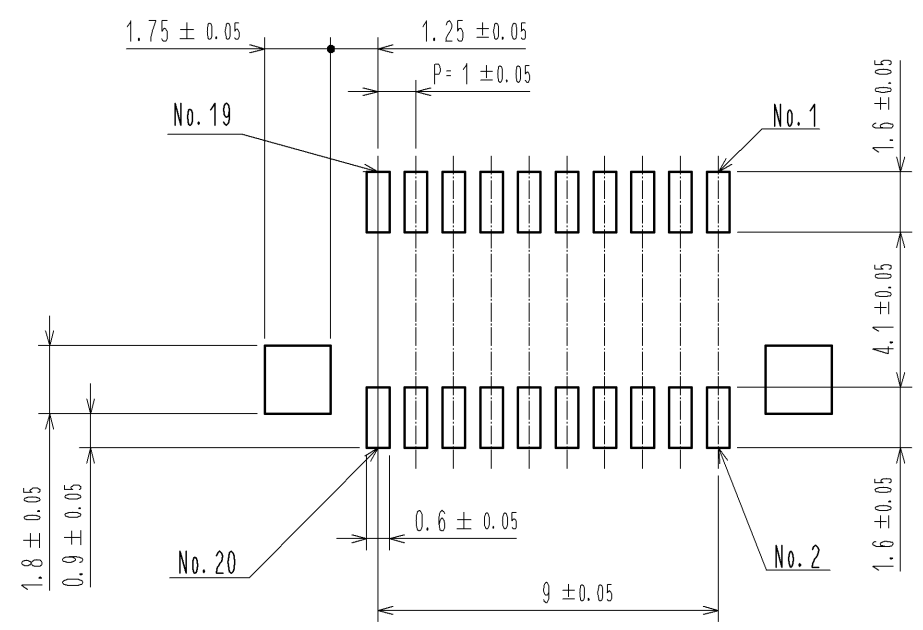
UNITS mm		SCALE 5 : 1	COUNT 	DESCRIPTION OF REVISIONS 2 DIS-H-008701	DESIGNED MI. SAKIMURA	CHECKED TS. KUMAZAWA	DATE 14. 04. 22
 HIROSE ELECTRIC CO., LTD.	APPROVED : KI. AKIYAMA	11. 12. 26	DRAWING NO.	EDC3-332132-01			
	CHECED : OM. MIYAMOTO	11. 12. 26	PART NO.	DF50-20DP-1H(51)			
	DESIGNED : TT. OHSAKO	11. 12. 01	CODE NO.	CL665-0016-5-51			
	DRAWN : TT. OHSAKO	11. 12. 01	 				

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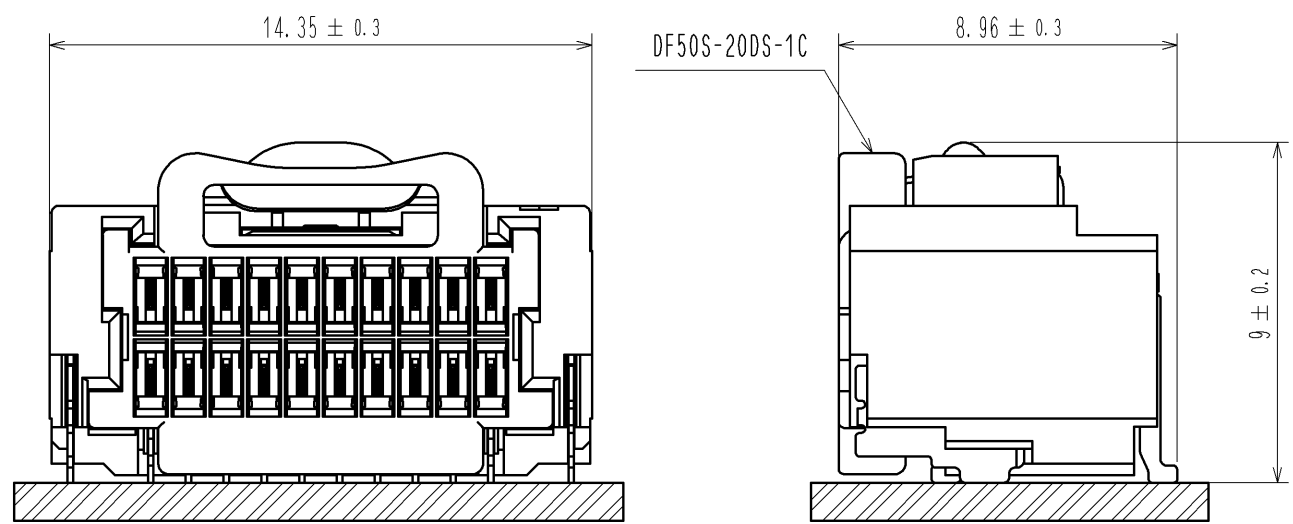
RECOMMENDED PCB LAYOUT
(MOUNTING SURFACE SIDE) (FREE)



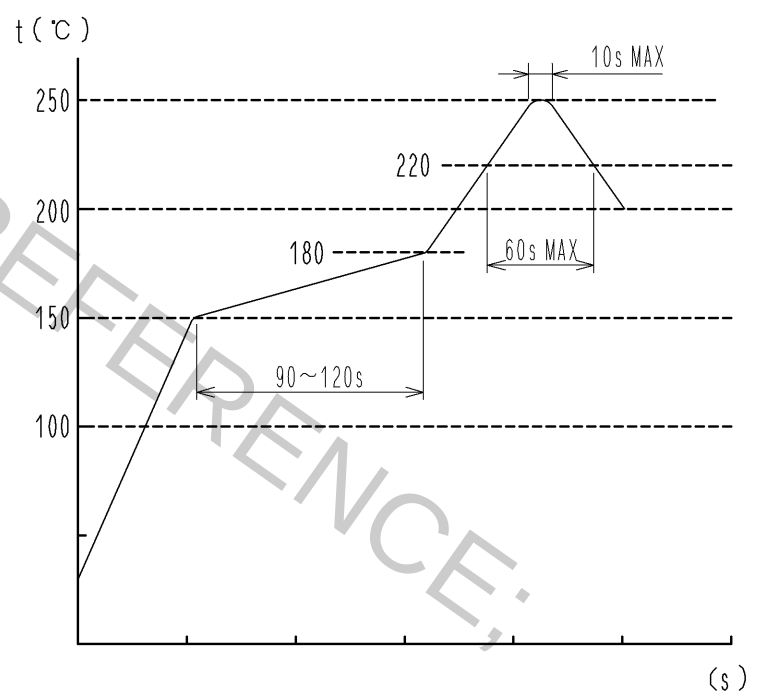
RECOMMENDED METAL MASK (FREE)
THICKNESS : 0.1mm
OPEN AREA RATIO:100%



MATING FIGURE (5 : 1)



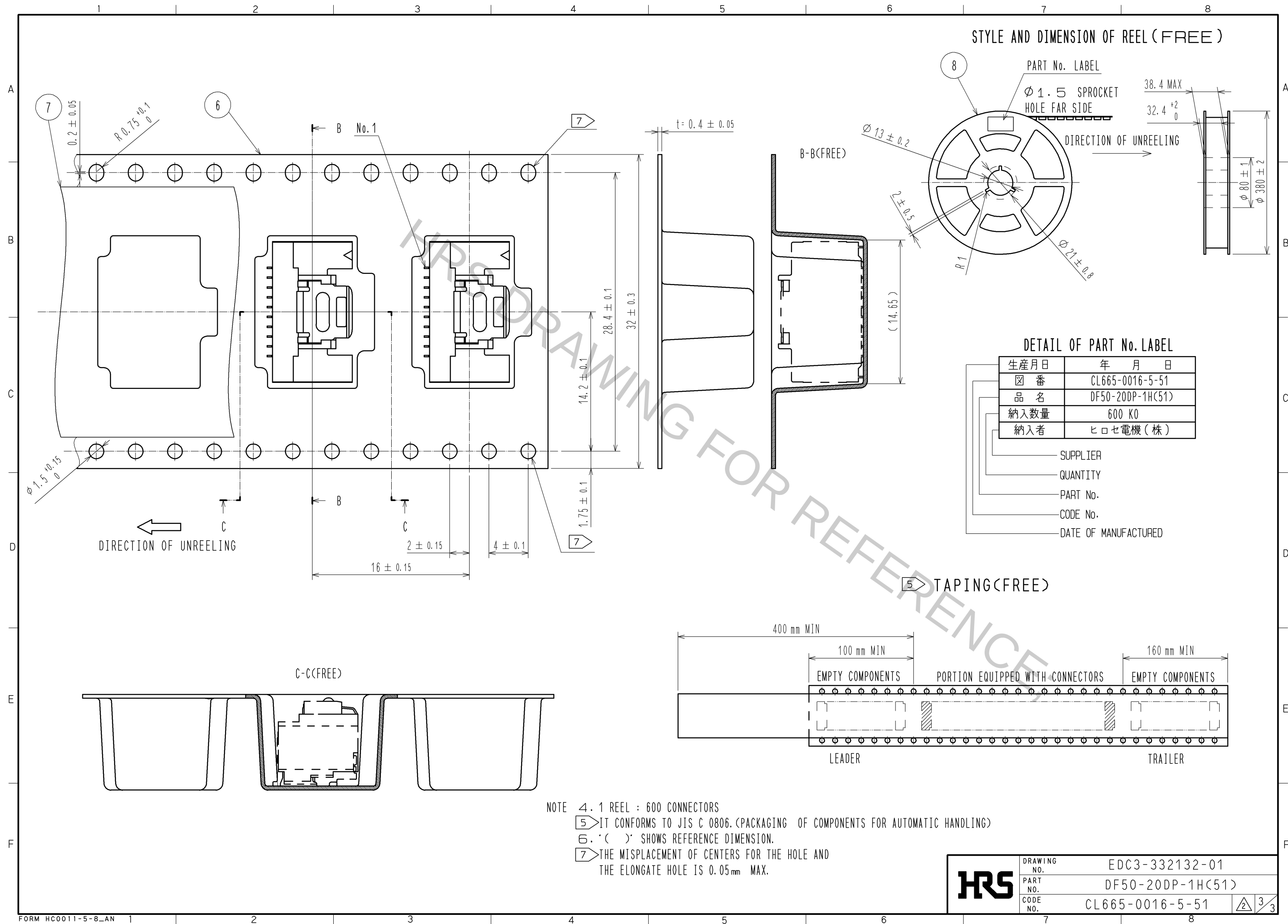
REFLOW TEMPERATURE PROFILE USING LEAD-FREE SOLDER PASTE (REFERENCE)



NUMBER OF REFLOW CYCLES: 2 CYCLES MAX.
THE TEMPERATURE OF THIS PROFILE IS MEASURED ON THE LEAD TERMINAL.

WE RECOMMEND PERFORMING AN EVALUATION UNDER THE MOUNTING
CONDITIONS YOU WILL BE USING BECAUSE IT COULD BE AFFECTED
BY ANY CONDITION:TYPE OF SOLDER PASTE, SIZE OF PCB, MOUNTING
MATERIAL etc..

HRS	DRAWING NO.	EDC3-332132-01
	PART NO.	DF50-20DP-1H(51)
	CODE NO.	CL665-0016-5-51
		2/3



HRS	DRAWING NO.	EDC3-332132-01
	PART NO.	DF50-20DP-1H(51)
	CODE NO.	CL665-0016-5-51
		2/3